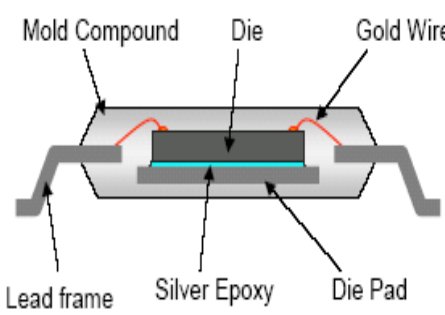


Material Declaration

Compliance Date: Sep./24/2020

RoHS Compliance: Yes

MSL: 3

Pin count /Package		48L TSOPI (12x20 mm)							
Model (Part) Number		AS6C3216A-55TIN							
Package Weight (mg)		535.995							
Composed parts	Purpose	Weight (mg)	%	ppm	Material	CAS No.	Weight (mg)	Material wt% of total Mass	Material wt% of Sub part
Chip	Wafer Circuit	25.83	4.82	48,191	Silicon (Si)	7440-21-3	25.830	4.819%	100.00%
Bonding Wire	Conductivity	0.536	0.10	1,000	Gold (Au)	7440-57-5	0.536	0.100%	100.00%
Die Attach	Conductivity	0.429	0.08	800	Silver Power	7440-22-4	0.322	0.060%	75.00%
					Epoxy resin A	9003-36-5	0.017	0.003%	4.00%
					Epoxy resin B	Trade secret	0.026	0.005%	6.00%
					Diluent A	Trade secret	0.017	0.003%	4.00%
					Diluent B	Trade secret	0.026	0.005%	6.00%
					Hardener	Trade secret	0.018	0.003%	4.25%
					Dicyandiamide	461-58-5	0.001	0.0002%	0.25%
					Organic peroxide	Trade secret	0.002	0.0004%	0.50%
Lead Frame	Base Metal	171.520	32.00	320,003	Copper (Cu)	7440-50-8	161.743	30.176%	94.30%
					Nickel (Ni)	7440-02-0	5.489	1.024%	3.20%
					Silicon (Si)	7440-21-3	1.372	0.256%	0.80%
					Magnesium (Mg)	7439-95-4	0.343	0.064%	0.20%
					Silver (Ag)	7440-22-4	2.573	0.480%	1.50%
Molding Compound	Chip Protection	321.600	60.00	600,006	Silica(Amorphous) A	60676-86-0	266.606	49.740%	82.90%
					Silica(Amorphous) B	7631-86-9	17.045	3.180%	5.30%
					Epoxy Resin A	Trade secret	16.080	3.000%	5.00%
					Epoxy Resin B	29690-82-2	4.824	0.900%	1.50%
					Phenol Resin	Trade secret	16.080	3.000%	5.00%
					Carbon Black	1333-86-4	0.965	0.180%	0.30%
Plating of lead frame	Solder Plating	16.080	3.00	30,000	Tin (Sn)	7440-31-5	16.078	3.000%	99.99%
					Lead (Pb)	7439-92-1	0.0016	0.0003%	0.01%